



IN THE UNITED STATES  
PATENT AND TRADEMARK OFFICE

PATENT APPLICATION

INVENTORS:

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CASE: 60-40-1-1

TITLE: STACKED MODULE PACKAGE

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EXAMINER DiLinh P. Nguyen

THE COMMISSIONER OF PATENTS AND TRADEMARKS  
WASHINGTON, D.C. 20231

SIR:

In response to the Office action mailed 08/28/2002 please enter the following  
amendments and consider the remarks that follow.

In the claims:

Please amend claim 1 to read:

1. A stacked MCM package comprising a substrate, a digital MCM on the  
substrate, an RF MCM on the digital MCM, and means electrically  
connecting the RF MCM to the substrate, and wherein the RF MCM and  
the digital MCM are electrically isolated.